EMD2FHA / UMD2NFHA / IMD2AFRA

NPN + PNP Complex Digital Transistors (Bias Resistor Built-in Transistors) Datasheet

AEC-Q101 Qualified

<For DTr1(NPN)>

Parameter	Value
V _{CC}	50V
I _{C(MAX.)}	100mA
R ₁	22kΩ
R ₂	22kΩ

<For DTr2(PNP)>

Parameter	Value
V_{CC}	-50V
I _{C(MAX.)}	-100mA
R ₁	22kΩ
R_2	22kΩ

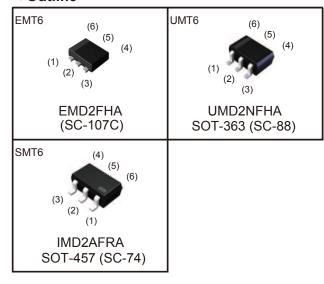
Features

- 1) Both the DTC124E chip and DTA124E chip in one package.
- 2) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of completely eliminating parasitic effects.
- 4) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 5) Lead Free/RoHS Compliant.

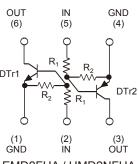
Application

Inverter circuit, Interface circuit, Driver circuit

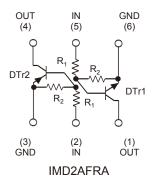
Outline



•Inner circuit



EMD2FHA / UMD2NFHA



Packaging specifications

- Luckaging opcomodations							
Part No.	Package	Package size (mm)	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit (pcs)	Marking
EMD2FHA	EMT6	1616	T2R	180	8	8,000	D2
UMD2NFHA	UMT6	2021	TR	180	8	3,000	D2
IMD2AFRA	SMT6	2928	T108	180	8	3,000	D2

● Absolute maximum ratings (Ta = 25°C)

Parameter		Symbol	DTr1(NPN)	DTr2(PNP)	Unit
Supply voltage		V_{CC}	50	-50	V
Input voltage		V_{IN}	-10 to +40	-40 to +10	V
Output current		Ι _ο	30	-30	mA
Collector current		I _{C(MAX.)} *1	100	-100	mA
Power dissination	EMD2FHA / UMD2NFHA	P _D *2	150 (Total)*3		mW
Power dissipation IMD2AFRA		r _D	300 (Total)*4		mW
Junction temperature		T _j	150		°C
Range of storage temperature		T_{stg}	−55 to +150		°C

●Electrical characteristics(Ta = 25°C) <For DTr1(NPN)>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input voltage	$V_{I(off)}$	$V_{CC} = 5V, I_{O} = 100 \mu A$	-	-	0.5	V
	$V_{I(on)}$	$V_{\rm O} = 0.2 V, I_{\rm O} = 5 {\rm mA}$	3.0	-	-	V
Output voltage	$V_{O(on)}$	$I_{O}/I_{I} = 10mA/0.5mA$	-	0.1	0.3	V
Input current	I _I	V _I = 5V	-	-	0.36	mA
Output current	I _{O(off)}	$V_{CC} = 50V, V_{I} = 0V$	-	-	0.5	μΑ
DC current gain	Gı	$V_O = 5V$, $I_O = 5mA$	56	-	-	-
Input resistance	R ₁	-	15.4	22	28.6	kΩ
Resistance ratio	R ₂ /R ₁	-	0.8	1	1.2	-
Transition frequency	f _T *1	$V_{CE} = 10V, I_{E} = -5mA$ f = 100MHz	-	250	-	MHz

●Electrical characteristics(Ta = 25°C) <For DTr2(PNP)>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input voltage	$V_{I(off)}$	$V_{CC} = -5V, I_{O} = -100 \mu A$	-	-	-0.5	V
	$V_{I(on)}$	$V_0 = -0.2V, I_0 = -5mA$	-3.0	-	-	V
Output voltage	$V_{O(on)}$	$I_{O}/I_{I} = -10\text{mA}/-0.5\text{mA}$	-	-0.1	-0.3	V
Input current	I _I	V₁ = −5V	-	-	-0.36	mA
Output current	I _{O(off)}	$V_{CC} = -50V, V_{I} = 0V$	-	-	-0.5	μΑ
DC current gain	G _I	$V_0 = -5V, I_0 = -5mA$	56	-	-	-
Input resistance	R ₁	-	15.4	22	28.6	kΩ
Resistance ratio	R ₂ /R ₁	-	0.8	1	1.2	-
Transition frequency	f _T *1	$V_{CE} = -10V, I_{E} = 5mA$ f = 100MHz	-	250	-	MHz

^{*1} Characteristics of built-in transistor

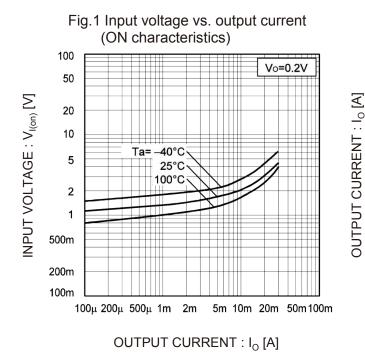


^{*2} Each terminal mounted on a reference footprint

^{*3 120}mW per element must not be exceeded.

^{*4 200}mW per element must not be exceeded.

●Electrical characteristic curves (Ta = 25°C) <For DTr1(NPN)>



(OFF characteristics) 10m Vcc=5V 5m 2m Ta=100°C 1m 25°C 500μ 200μ 100μ 50μ 20μ 10μ 5μ 2μ 1μ 2.5 0 0.5 1.0 1.5 2.0 3.0 INPUT VOLTAGE : $V_{I(off)}[V]$

Fig.2 Output current vs. input voltage

Fig.3 Output current vs. output voltage

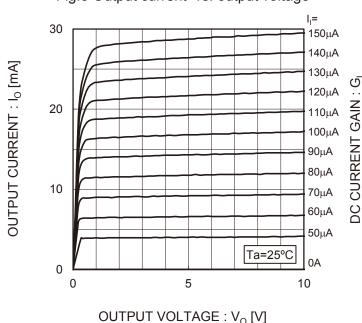


Fig.4 DC current gain vs. output current

OUTPUT CURRENT : Io [A]

5m 10m 20m

50m 100m

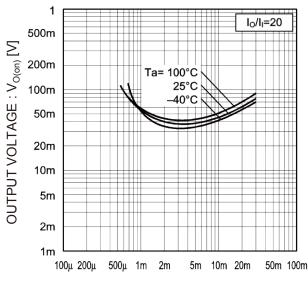
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 500μ 1m 2m

100μ 200μ

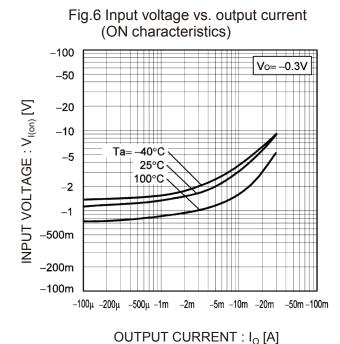
●Electrical characteristic curves(Ta = 25°C) <For DTr1(NPN)>

Fig.5 Output voltage vs. output current



OUTPUT CURRENT : Io [A]

●Electrical characteristic curves (Ta = 25°C) <For DTr2(PNP)>



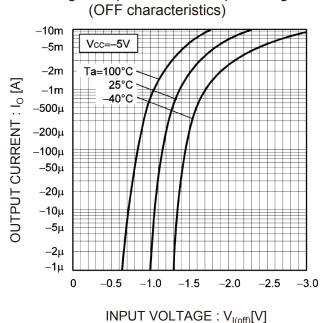


Fig.7 Output current vs. input voltage

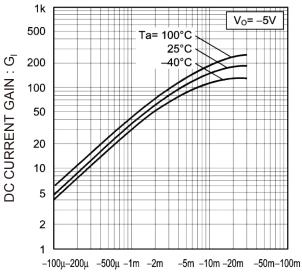
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●Electrical characteristic curves (Ta = 25°C) <For DTr2(PNP)>

Fig.8 Output current vs. output voltage

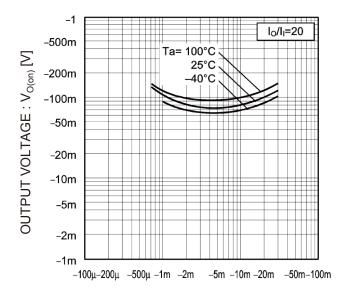
-30 Ta=25°C -130μΑ OUTPUT CURRENT : Io [mA] -120μA -25 -110µA -20 -90μΑ -15 -80μΑ -70μA -10 -60μA -50μΑ -5 -40μΑ 0 0 -5 -10 OUTPUT VOLTAGE: Vo [V]

Fig.9 DC current gain vs. output current



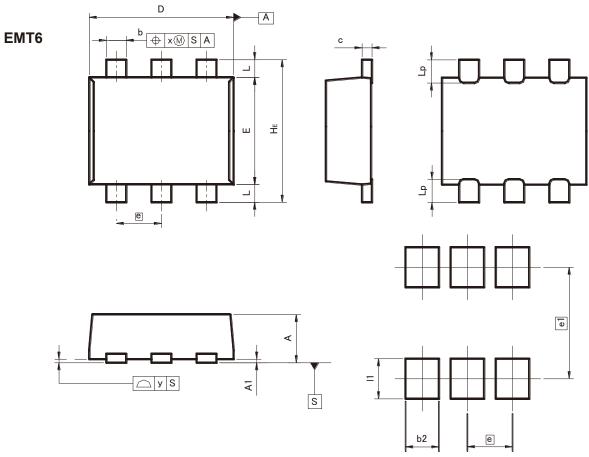
OUTPUT CURRENT : Io [A]

Fig.10 Output voltage vs. output current



OUTPUT CURRENT : I_O [A]

●Dimensions (Unit : mm)



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

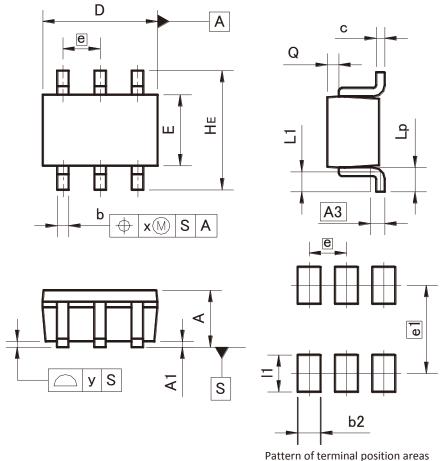
DIM	MILIMI	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
С	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
е	0.50		0.0	20
HE	1.50	1.70	0.059	0.067
L	0.10	0.30	0.004	0.012
Lp	_	0.35	ı	0.014
х	_	0.10	_	0.004
У	_	0.10	_	0.004

DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2	_	0.37	_	0.015
e1	1.25		0.0	49
l1	_	0.45	_	0.018

Dimension in mm / inches

●Dimensions (Unit : mm)





Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

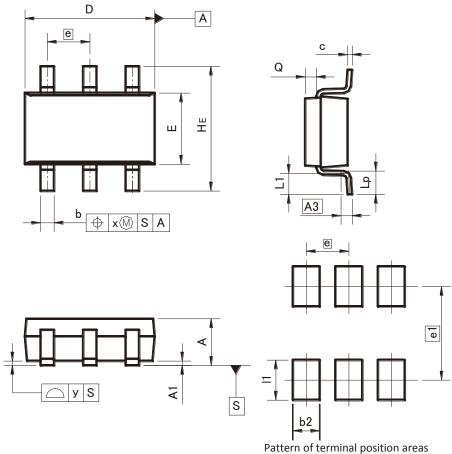
DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.3	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	65	0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
Х	_	0.10	_	0.004
У	_	0.10	_	0.004

DIM MILIME		ETERS	INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2	_	0.40	_	0.016
e1	1.55		0.0	61
l1	_	0.65	-	0.026

Dimension in mm / inches

● **Dimensions** (Unit: mm)





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.3	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	_	0.20	_	0.008
У	_	0.10	_	0.004

DIM	MILIMETERS		RS INCHES	
DIM	MIN	MAX	MIN	MAX
b2		0.60	ı	0.024
e1	2.10		0.0	83
l1	_	0.90	_	0.035

Dimension in mm / inches

Notice

Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

Ì	JÁPAN	USA	EU	CHINA
Γ	CLASSⅢ	CLASSII	CLASS II b	CLASSIII
Γ	CLASSIV		CLASSⅢ	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

QR code printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

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Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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